# **SPECIFICATION**

| CUSTON       | iek :      |        |              |             |  |
|--------------|------------|--------|--------------|-------------|--|
| MODUL        | E NO.:     | ZX3    | 20240R-ʻ     | rmi -tz#    |  |
| APPROV       |            | PCB VE | RSION:       | DATA:       |  |
| SALES BY     | APPROVED B | Y C    | HECKED BY    | PREPARED BY |  |
| ISSUED DATE: |            |        |              |             |  |
|              |            |        | MODLE NO :   |             |  |
| RECORDS      | OF REVISIO | N      | DOC. FIRST I | SSUE        |  |

| 北京      | 中显电子有限公司   | www.zxlcd.c         | <u>Com</u> TEL/FAX:010-82626833,51601226 |
|---------|------------|---------------------|--|
| VERSION | DATE       | REVISED<br>PAGE NO. | SUMMARY                                  |
| 0       | 2007.06.28 |                     | First issue                              |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |
|         |            |                     |  |

## **Contents**

- 1. Module classification information
- 2.Precautions in Use of LCM
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9. Timing Characteristics
- 10.Reliability
- 11.Backlight Information
- 12.Inspection specification
- 13. Material List of Components for RoHs

### **1.Module Classification Information**

 $\underline{Z} \underline{X} \underline{3} \underline{2} \underline{0} \underline{2} \underline{4} \underline{0} \quad \underline{R} - \underline{T} \underline{M} \underline{I} - \underline{T} \underline{Z} \underline{\#}$ 

1) 2

(3)

4

567

8

① Brand: CORPORATION

② Display Type: H→Character Type, G→Graphic Type

③ Display Font: 320 \* 240 Dots

Model serials number

 $\bigcirc$  Backlight Type : N $\rightarrow$ Without backlight T $\rightarrow$ LED, White

 $B\rightarrow EL$ , Blue green  $A\rightarrow LED$ , Amber

 $D\rightarrow EL$ , Green  $R\rightarrow LED$ , Red

 $W\rightarrow EL$ , White  $O\rightarrow LED$ , Orange

 $F \rightarrow CCFL$ , White  $G \rightarrow LED$ , Green

 $Y\rightarrow$ LED, Yellow Green  $S\rightarrow$ LED, High light white

© LCD Mode : B→TN Positive, Gray T→FSTN Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

② LCD Polarize Type/ A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Temperature range/ D→Reflective, N.T, 12:00 K→Transflective, W.T, 12:00 View direction

G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00

J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code
T: Negative Voltage generator on board and temperature

compensation

Z: NT7086

#: Fit with in the ROHS directives and regulations

## 2. Precautions in Use of LCD Module

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD Module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.

## 3. General Specification

| ITEM              | STANDARD VALUE                   | UNIT |
|-------------------|----------------------------------|------|
| Number of dots    | 320x240                          | dots |
| Outline dimension | 160.0(W)x 109.0(H)x 11.0max(T)   | mm   |
| View area         | 122.0(W)x 92.0(H)                | mm   |
| Active area       | 115.18(W)x 86.38(H)              | mm   |
| Dot size          | 0.49 (W)x 0.5 (H)                | mm   |
| Dot pitch         | 0.54(W)x 0.54(H)                 | mm   |
| LCD type          | STN Negative, Transmissive, Blue |      |
| View direction    | 6 o'clock                        |      |
| Backlight         | LED, White                       |      |

# 4. Absolute Maximum Ratings

| ITEM                     | SYMBOL              | MIN. | TYP.        | MAX.        | UNIT                   |
|--------------------------|---------------------|------|-------------|-------------|------------------------|
| Operating Temperature    | $T_{OP}$            | -20  | _           | +70         | $^{\circ}\!\mathbb{C}$ |
| Storage Temperature      | $T_{ST}$            | -30  | _           | +80         | $^{\circ}$             |
|                          |                     |      |             |             |                        |
| Input Voltage            | V <sub>I</sub>      | 0    | <del></del> | $V_{ m DD}$ | V                      |
| Supply Voltage For Logic | $V_{\mathrm{DD}}$   | 0    |             | 6.5         | V                      |
| Supply Voltage For LCD   | $V_{DD}$ - $V_{EE}$ | 0    | _           | 32          | V                      |

## **5.** Electrical Characteristics

| ITEM               | SYMBOL              | CONDITION | MIN.        | TYP. | MAX.        | UNIT |
|--------------------|---------------------|-----------|-------------|------|-------------|------|
| Logic Voltage      | $V_{DD}$ - $V_{SS}$ | _         | 4.75        | 5.0  | 5.25        | V    |
|                    |                     | Ta =20°℃  | _           | _    | 25.0        | V    |
| Supply Voltage For | $V_{DD}$ - $V_{O}$  | Ta=25°C   | _           | 23.8 | _           | V    |
| LCD                |                     | Ta=70°C   | 23.0        | _    | _           | V    |
| Input High Volt.   | $V_{\mathrm{IH}}$   | _         | $0.5V_{DD}$ | _    | $V_{ m DD}$ | V    |
| Input Low Volt.    | $V_{IL}$            | _         | 0           | _    | $0.2V_{DD}$ | V    |
| Output High Volt.  | $V_{\mathrm{OH}}$   | _         | 2.4         | _    | _           | V    |
| Output Low Volt.   | V <sub>OL</sub>     | _         | _           | _    | 0.4         | V    |
| Supply Current     | $I_{\mathrm{DD}}$   | 5.0V      | _           | 25   | _           | mA   |

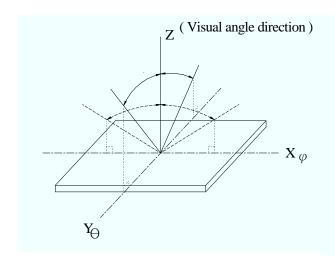
## 6. Optical Characteristics

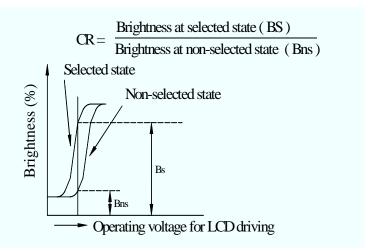
| ITEM           | SYMBAL        | CONDITION | MIN | TYP | MAX | UNIT |
|----------------|---------------|-----------|-----|-----|-----|------|
| View Angle     | (V) θ         | CR≧2      | 20  | _   | 40  | deg. |
|                | (H) $\varphi$ | CR≧2      | -30 | _   | 30  | deg. |
| Contrast Ratio | CR            | _         | _   | 3   | _   | _    |
| D              | T rise        | _         | _   | 150 | 200 | ms   |
| Response Time  | T fall        | _         | _   | 150 | 200 | ms   |

#### **6.1 Definitions**

#### **View Angles**

#### **Contrast Ratio**



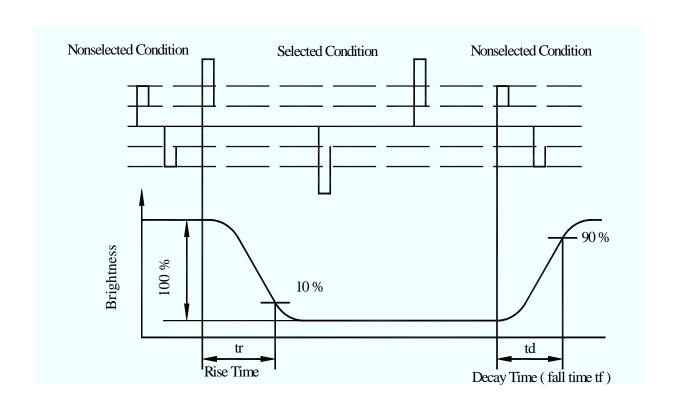


**Response time** 

## 7. Interface Description

| Pin No. | Symbol  | Level      | Description             |
|---------|---------|------------|-------------------------|
| 1       | GND     | H/L        | Power Supply(+5V)       |
| 2       | Vcc     | 5.0V       | Power supply for Logic  |
| 3       | $V_{O}$ | (Variable) | Driving voltage for LCD |
| 4       | RS      | H/L        | Register select signal  |

| 北  | 京中显电子有网  | 艮公司 | <u>www.zxlcd.com</u> TEL/FAX:010-82626833,51601226 |
|----|----------|-----|--|
| 5  | RD       | H/L | Data write   |
| 6  | WR       | H/L | Data write   |
| 7  | DB0      | H/L | Frame reverse signal(alternate signal)             |
| 8  | DB1      | H/L | Data bus line                                      |
| 9  | DB2      | H/L | Data bus line                                      |
| 10 | DB3      | H/L | Data bus line                                      |
| 11 | DB4      | H/L | Data bus line                                      |
| 12 | DB5      | H/L | Data bus line                                      |
| 13 | DB6      | H/L | Data bus line                                      |
| 14 | DB7      | H/L | Data bus line                                      |
| 15 | /CS      | H/L | Chip Enable  |
| 16 | RST      | L   | Reset  |
| 17 | $V_{EE}$ | _   | Power supply for LCD                               |
| 18 | BUSY     | _   | Ra8803 start                                       |
| 19 | INT      | _   | Program able interrupt for 8803                    |



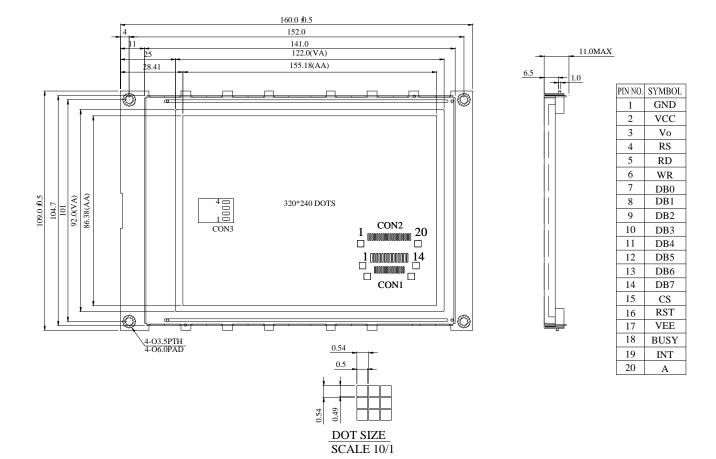
Power Supply for B/L

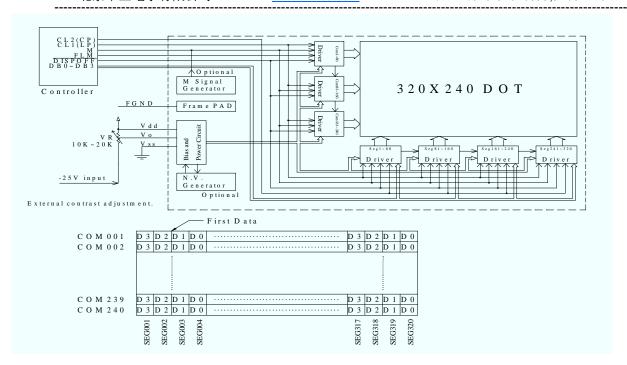
20

A

------

## 8. Contour Drawing & Block diagram





# 9. Timing Characteristics

9.1.Common & Segment interface timing:

| ITEM               | symbol  | Test Condition | Min. | Тур. | Max. | Units |
|--------------------|---------|----------------|------|------|------|-------|
| Clock Cycle        | tC      | Fig.1          | 100  |      |      | ns    |
| CP Pulse Width     | tWC     | Fig.1          | 50   | _    | _    | ns    |
| LP Pulse Width     | tWL     | Fig.1          | 50   | _    |      | ns    |
| Data Set Up Time   | tDSU    | Fig.1          | 30   | _    | _    | ns    |
| Data Hold Time     | tDHD    | Fig.1          | 30   | _    | _    | ns    |
| CP Rise/Fall Time  | tr,tf   | Fig.1          | _    | _    | 50   | ns    |
| CP to LOAD         | tCL     | Fig.1          | 80   | _    | _    | ns    |
| LOAD to CP         | tLC     | Fig.1          | 110  | _    | _    | ns    |
| LP Pulse Width     | tLW     | Fig.1          | 50   | _    | _    | ns    |
| CL1 Pulse Width    | tCW     | Fig.2          | 63   | _    | _    | ns    |
| Data Set Up Time   | tDSU2   | Fig.2          | 100  | _    | _    | ns    |
| Data Hold Time     | tDHD2   | Fig.2          | 100  | _    | _    | ns    |
| CL1 Rise/Fall Time | tr2,tf2 | Fig.2          | _    | _    | 50   | ns    |

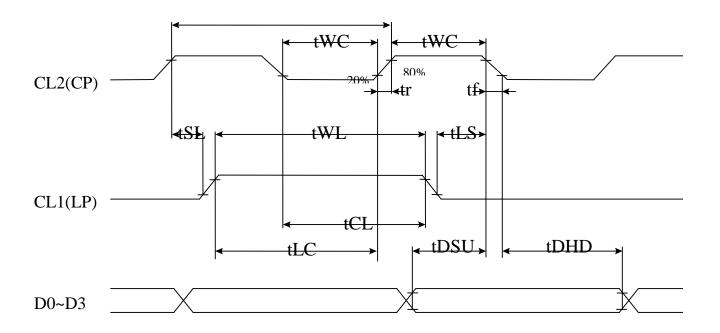


Fig 1. SEGMENT TIMING

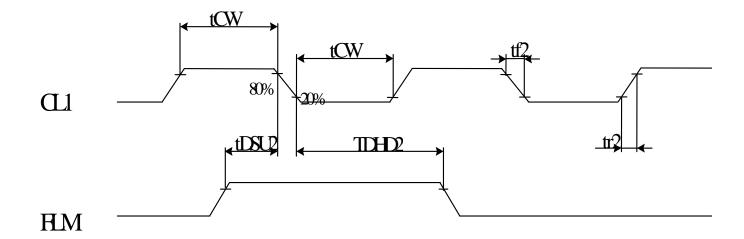
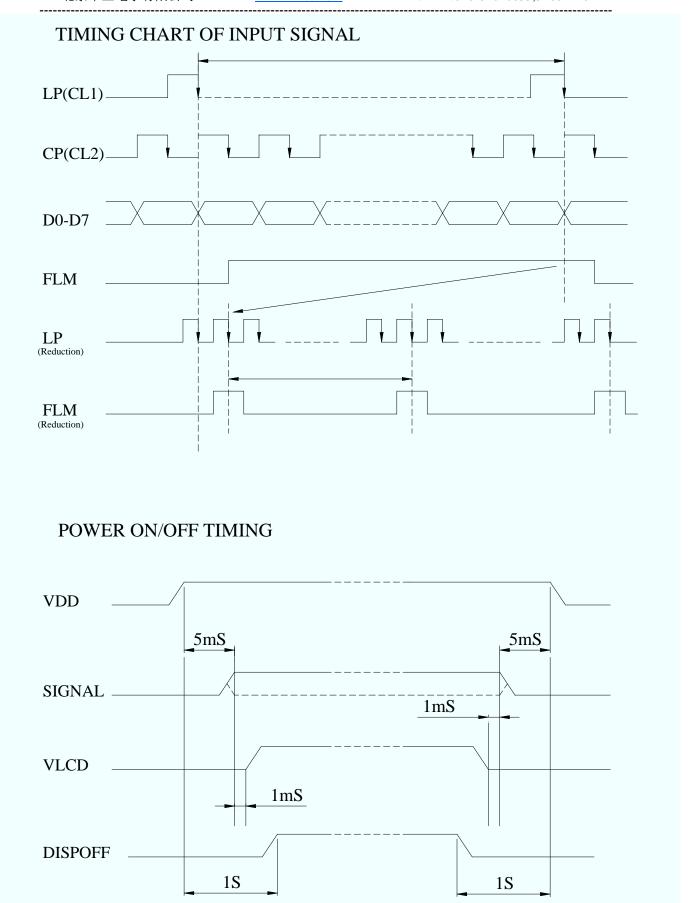


Fig 2 COMMON TIMING



## 10.RELIABILITY

#### Content of Reliability Test (wide temperature, -20°C~70°C)

| Environmental Test      |  |                          |      |  |  |  |  |  |
|-------------------------|--|--------------------------|------|--|--|--|--|--|
| Test Item               | Content of Test  | <b>Test Condition</b>    | Note |  |  |  |  |  |
| High Temperature        | Endurance test applying the high storage temperature for a   | 80°C                     | 2    |  |  |  |  |  |
| storage                 | long time.   | 200hrs                   | 2    |  |  |  |  |  |
| Low Temperature         | Endurance test applying the high storage temperature for a   | -30°C                    | 1,2  |  |  |  |  |  |
| storage                 | long time.   | 200hrs                   | 1,2  |  |  |  |  |  |
| High Temperature        | Endurance test applying the electric stress (Voltage &       | <br> 70℃                 |      |  |  |  |  |  |
| Operation               | Current) and the thermal stress to the element for a long    | 200hrs                   |      |  |  |  |  |  |
| Operation               | time.  | Zoonis                   |      |  |  |  |  |  |
| Low Temperature         | Endurance test applying the electric stress under low        | -20°C                    | 1    |  |  |  |  |  |
| Operation               | temperature for a long time.                                 | 200hrs                   | 1    |  |  |  |  |  |
|                         | The module should be allowed to stand at 60°C,90%RH          |                          |      |  |  |  |  |  |
| High Temperature/       | max  | 60°C,90%RH               | 1,2  |  |  |  |  |  |
| Humidity Operation      | For 96hrs under no-load condition excluding the polarizer,   | 96hrs                    | 1,2  |  |  |  |  |  |
|                         | Then taking it out and drying it at normal temperature.      |                          |      |  |  |  |  |  |
|                         | The sample should be allowed stand the following 10 cycles   |                          |      |  |  |  |  |  |
|                         | of operation   |                          |      |  |  |  |  |  |
| Thermal shock           | -20°C 25°C 70°C  | -20°C/70°C               |      |  |  |  |  |  |
| resistance              |  | 10 cycles                |      |  |  |  |  |  |
|                         | 30min 20min  |                          |      |  |  |  |  |  |
|                         | 1 cycle  |                          |      |  |  |  |  |  |
|                         |  | Total fixed              |      |  |  |  |  |  |
|                         |  | amplitude: 1.5mm         |      |  |  |  |  |  |
|                         |  | Vibration                |      |  |  |  |  |  |
|                         | Endurance test applying the vibration during transportation  | Frequency:               |      |  |  |  |  |  |
| Vibration test          | and using.   | 10~55Hz                  | 3    |  |  |  |  |  |
|                         | and using.   | One cycle 60 seconds     |      |  |  |  |  |  |
|                         |  | to 3 directions of       |      |  |  |  |  |  |
|                         |  | X,Y,Z for                |      |  |  |  |  |  |
|                         |  | Each 15 minutes          |      |  |  |  |  |  |
| Quarte of the state of  |  | VS=800V,RS=1.5k $\Omega$ |      |  |  |  |  |  |
| Static electricity test | Endurance test applying the electric stress to the terminal. | CS=100Pf 1 time          |      |  |  |  |  |  |

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

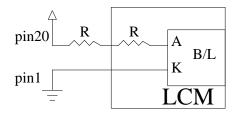
## 11. Backlight Information

**Specification** 

|                 | GT 13 5 D O T |     |     |     |                   |                |
|-----------------|---------------|-----|-----|-----|-------------------|----------------|
| PARAMETER       | SYMBOL        | MIN | TYP | MAX | UNIT              | TEST CONDITION |
| Supply Current  | ILED          | 120 | 160 | 225 | mA                | V=3.5V         |
| Supply Voltage  | V             | 3.4 | 3.5 | 3.6 | V                 | _              |
| Reverse Voltage | VR            | _   | _   | 10  | V                 | _              |
| Luminous        | IV            | 260 | 280 | _   | CD/M <sup>2</sup> | ILED=160mA     |
| Intensity       |               |     |     |     |                   |                |
| Wave Length     | λp            |     |     | _   | nm                | ILED=160mA     |
| Life Time       | _             | _   | 50K | _   | Hr.               | ILED≤160mA     |
| Color           | White         | •   | •   |     | •                 |                |

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Drive from pin1,pin20



# 12. Inspection specification

| NO | Item   | Criterion   |                 |  |  |     |  |  |
|----|--|---|-----------------|--|--|-----|--|--|
| 01 | Electrical<br>Testing  | <ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol> |                 |  |  |     |  |  |
| 02 | Black or white<br>spots on<br>LCD<br>(display<br>only)                   | <ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>  |                 |  |  |     |  |  |
| 03 | LCD black<br>spots, white<br>spots,<br>contaminati<br>on<br>(non-display | 3.1 Round type $\Phi = (x + y)$ 3.2 Line type:  | y)/2 <u>↓</u> Y | SIZE<br>$\Phi \le 0.10$<br>$0.10 < \Phi \le 0.20$<br>$0.20 < \Phi \le 0.25$<br>$0.25 < \Phi$ | Acceptable Q TY Accept no dense  2 1 0  Acceptable Q TY Acceptable Q TY Accept no dense  2 As round type | 2.5 |  |  |
| 04 | Polarizer<br>bubbles   |   |                 | Size $\Phi$ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$      | Acceptable Q TY Accept no dense 3 2 0  | 2.5 |  |  |

#### Total Q TY

3

If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.

2.5

NO Item Criterion AQL

05 Scratches

Follow NO.3 LCD black spots, white spots, contamination

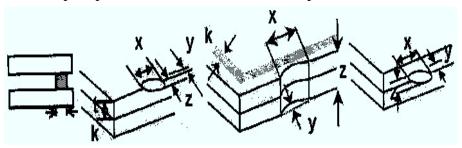
Symbols Define:

x: Chip lengthy: Chip widthz: Chip thicknessk: Seal widtht: Glass thicknessa: LCD side length

L: Electrode pad length:

6.1 General glass chip:

6.1.1 Chip on panel surface and crack between panels:



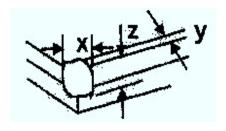
06 Chipped glass

z: Chip thickness y: Chip width x: Chip length  $Z \le 1/2t$  Not over viewing area  $x \le 1/8a$ 

 $1/2t < z \le 2t$  Not exceed 1/3k  $x \le 1/8a$ 

⊙ If there are 2 or more chips, x is total length of each chip.

#### 6.1.2 Corner crack:



z: Chip thickness y: Chip width x: Chip length  $Z \le 1/2t$  Not over viewing area  $x \le 1/8a$   $1/2t < z \le 2t$  Not exceed 1/3k  $x \le 1/8a$ 

⊙ If there are 2 or more chips, x is the total length of each chip.

NO Item Criterion AQL

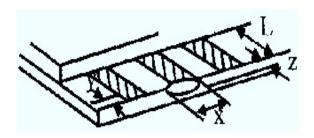
Symbols:

x: Chip lengthy: Chip widthz: Chip thicknessk: Seal widtht: Glass thicknessa: LCD side length

L: Electrode pad length

6.2 Protrusion over terminal:

6.2.1 Chip on electrode pad:



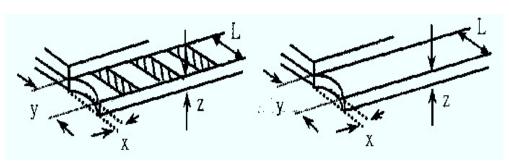
y: Chip width y≤0.5mm

x: Chip length  $x \le 1/8a$ 

z: Chip thickness  $0 < z \le t$ 

6.2.2 Non-conductive portion:

Glass 06 cra ck



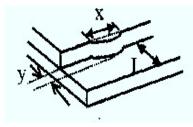
y: Chip width  $y \le L$ 

x: Chip length  $x \le 1/8a$ 

z: Chip thickness  $0 < z \le t$ 

2.5

- ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
- ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.
- 6.2.3 Substrate protuberance and internal crack.



y: width x: length  $y \le 1/3L$   $x \le a$ 

| NO | Item               | Criterion   | AQI         |
|----|--------------------|---|-------------|
| 07 | Cracked glass      | The LCD with extensive crack is not acceptable.   | 2.5         |
| 08 | Backlight elements | <ul><li>8.1 Illumination source flickers when lit.</li><li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li></ul> | 0.65<br>2.5 |
|    |                    | 8.3 Backlight doesn't light or color wrong.   | 0.65        |
| 09 | Bezel              | <ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>              | 2.5<br>0.65 |
|    |                    | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination.   | 2.5         |
|    |                    | <ul><li>10.2 COB seal surface may not have pinholes through to the IC.</li><li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li></ul> | 2.5<br>0.65 |
|    |                    | 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.   | 2.5         |
|    | PCB、COB            | 10.5 No oxidation or contamination PCB terminals.   | 2.5         |
| 10 |                    | 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.  | 0.65        |
|    |                    | 10.7 The jumper on the PCB should conform to the product characteristic chart.  | 0.65        |
|    |                    | 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.   | 2.5         |
|    |                    | 10.9 The Scraping testing standard for Copper Coating of PCB  X * Y <= 2mm <sup>2</sup>   | 2.5         |
|    |                    | 11.1 No un-melted solder paste may be present on the PCB.   | 2.5         |
| 11 | Soldering          | 11.2 No cold solder joints, missing solder connections, oxidation or icicle.  | 2.5         |
|    |                    | 11.3 No residue or solder balls on PCB.   | 2.5         |

0.65

11.4 No short circuits in components on PCB.

| NO | Item       | Criterion   | AQI  |
|----|------------|---|------|
|    | General    | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. | 2.5  |
|    |            | 12.2 No cracks on interface pin (OLB) of TCP.                                     | 0.65 |
|    |            | 12.3 No contamination, solder residue or solder balls on product.                 | 2.5  |
|    |            | 12.4 The IC on the TCP may not be damaged, circuits.                              | 2.5  |
|    |            | 12.5 The uppermost edge of the protective strip on the interface pin              | 2.5  |
|    |            | must be present or look as if it cause the interface pin to                       |      |
|    |            | sever.  |      |
| 12 |            | 12.6 The residual rosin or tin oil of soldering (component or chip                | 2.5  |
|    | appearance | component) is not burned into brown or black color.                               |      |
|    |            | 12.7 Sealant on top of the ITO circuit has not hardened.                          | 2.5  |
|    |            | 12.8 Pin type must match type in specification sheet.                             | 0.65 |
|    |            | 12.9 LCD pin loose or missing pins.   | 0.65 |
|    |            | 12.10 Product packaging must the same as specified on packaging                   | 0.65 |
|    |            | specification sheet.  |      |
|    |            | 12.11 Product dimension and structure must conform to product                     | 0.65 |
|    |            | specification sheet.  |      |

### 13. Material List of Components for RoHs

1. Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

| Material   | (Cd)       | (Pb)        | (Hg)        | (Cr6+)      | PBBs        | PBDEs       |
|--|------------|-------------|-------------|-------------|-------------|-------------|
| Limited<br>Value                                 | 100<br>ppm | 1000<br>ppm | 1000<br>ppm | 1000<br>ppm | 1000<br>ppm | 1000<br>ppm |
| Above limited value is set up according to RoHS. |            |             |             |             |             |             |

#### 2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

------

(3) Temp. curve of reflow, max. Temp. : 235±5℃;

LCM Sample Estimate Feedback Sheet

#### Module Number: Page: 1 1 · Panel Specification: 1. ☐ Pass Panel Type: $\bigcap$ NG, 2. View Direction: ☐ Pass □ NG, 3. Numbers of Dots: ☐ Pass ☐ NG ,\_\_\_\_\_ 4. View Area: ☐ Pass □ NG, 5. Active Area: ☐ Pass ☐ NG ,\_\_\_\_\_ □ NG ,\_\_\_\_\_ 6. Operating Temperature: Pass 7. Storage Temperature: ☐ Pass □ NG ,\_\_\_\_\_ 8. Others: 2 · Mechanical Specification: PCB Size: 1. Pass □ NG, 2. Frame Size: ☐ Pass □ NG ,\_\_\_\_\_ 3. Materal of Frame: Pass □ NG ,\_\_\_\_\_ 4. Connector Position: ☐ Pass $\bigcap$ NG, 5. Fix Hole Position: ☐ Pass $\bigcap$ NG, ☐ Pass 6. Backlight Position: $\bigcap$ NG, 7. Thickness of PCB: ☐ Pass □ NG ,\_\_\_\_\_ □ NG ,\_\_\_\_\_ 8. Height of Frame to PCB: ☐ Pass 9. Height of Module: Pass □ NG ,\_\_\_\_\_ 10. Others: $\bigcap$ NG, ☐ Pass **3** • Relative Hole Size :

| 1. | Pitch of Connector:     | Pass   | ☐ NG , |
|----|-------------------------|--------|--------|
| 2. | Hole size of Connector: | ☐ Pass | □ NG , |

- 3. Mounting Hole size: ☐ Pass □ NG ,\_\_\_\_\_ 4. Mounting Hole Type: Pass NG,
- 5. Others: □ NG ,\_\_\_\_ Pass

#### 4 · Backlight Specification:

| l. | B/L Type:  | Pass   | □ NG ,       |
|----|------------|--------|--------------|
| 2. | B/L Color: | ☐ Pass | $\sqcap$ NG, |

- 3. B/L Driving Voltage (Reference for LED Type) : 

  Pass  $\square$  NG,  $\bigcap$  NG, 4. B/L Driving Current: ☐ Pass
- 5. Brightness of B/L: Pass Pass □ NG ,\_\_\_\_\_ 6. B/L Solder Method: Pass
- NG ,\_\_\_\_\_ 7. Others: Pass  $\square$  NG,

#### >> Go to page 2 <<

|                 |                                 | •      |          |  |
|-----------------|---------------------------------|--------|----------|--|
| Module Number : |                                 |        | Page: 2  |  |
|                 | Electronic Characteristics of M |        | 1 agt. 2 |  |
| 1.              | Input Voltage:                  | Pass   | □ NG ,   |  |
| 2.              | Supply Current:                 | Pass   | □ NG ,   |  |
| 3.              | Driving Voltage for LCD:        | Pass   | □ NG ,   |  |
| 4.              | Contrast for LCD:               | Pass   | □ NG ,   |  |
| 5.              | B/L Driving Method:             | ☐ Pass | □ NG ,   |  |
| 6.              | Negative Voltage Output:        | ☐ Pass | □ NG ,   |  |
| 7.              | Interface Function:             | ☐ Pass | □ NG ,   |  |
| 8.              | LCD Uniformity:                 | ☐ Pass | □ NG ,   |  |
| 9.              | ESD test:                       | ☐ Pass | □ NG ,   |  |
| 10.             | Others:                         | Pass   | □ NG ,   |  |
| 6 · <u>S</u>    | Summary :                       |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |
|                 |                                 |        |          |  |